ATTY DOCKET NO. SERIAL NO EN9-97-075US INFORMATION DISCLOSURE CITATION Francis J. Downes et al. (Use several sheets if necessary) GROUP FILING **U.S. PATENT DOCUMENTS EXAMINER** FILING DATE SUBCLASS DOCUMENT NUMBER DATE NAME CLASS INITIAL IF APPROPRIATE 5,072,075 12/1991 Lee et al. 5,121,190 6/1992 Hsiao et al. 5,483,421 1/1996 Gedney et al. 11/1996 5,574,630 Kresge et al. 5,615,087 3/1997 Wieloch 8/1998 5,798,563 Feilchenfeld et al. 5,894,173 4/1999 Jacobs et al. 5,900,675 5/1999 Appelt et al. 4,882,454 11/1989 Peterson et al. 5,982,630 11/1999 Bhatia 7/1999 5,926,377 Nakao et al. **FOREIGN PATENT DOCUMENTS** TRANSLATION DOCUMENT NUMBER DATE COUNTRY CLASS SUBCLASS YES NO 9-232376 9/1997 Japan 10-209347 8/1998 Japan 11-87560 3/1999 Japan 2000-22071 1/2000 Japan 6-112271 4/1994 Japan OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.) IBM Technical Disclosure Bulletin, Vol. 32, No. 3B, August 1989, "MULTILAYER POLYMER SUBSTRATE FOR DIRECT CHIP ATTACHMENT." PROCESS CONSIDERATIONS IN THE FABRICATION OF TEFLON PRINTED CIRCUIT BOARDS, Light et al., 1994 Proceedings, 44 Electronic Components & Technology Conference, 5/94. **EXAMINER DATE CONSIDERED** EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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